



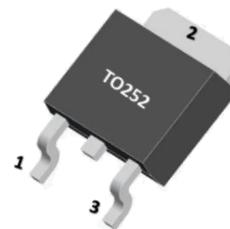
HY10N10

N-CHANNEL POWER MOSFET

10A, 100V N-CHANNEL POWER MOSFET

■ DESCRIPTION

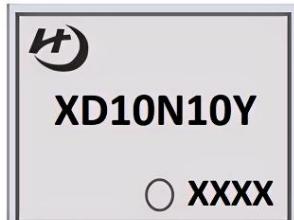
The XD10N10Y provide excellent RDS(ON), low gate charge and operation with low gate voltages. This device is suitable for use as a load switch or in PWM applications.



■ FEATURES

- * Excellent package for good heat dissipation
- * Ultra low gate charge
- * Low reverse transfer capacitance
- * Fast switching capability
- * Avalanche energy specified

■ MARKING



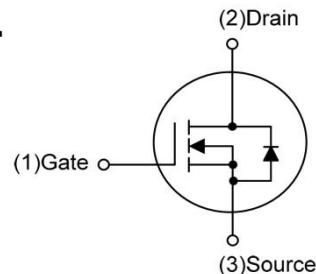
: HY LOGO

XD10N10Y=Device Code

XXXX=Date Code

Solid Dot=Green molding compound

SYMBOL



■ ABSOLUTE MAXIMUM RATINGS(TA=25°C, unless otherwise specified.)

SYMBOL	PARAMETER	RATINGS	UNIT	
V _{DSS}	Drain-Source Voltage	100	V	
V _{GSS}	Gate-Source Voltage	±20	V	
I _D	Continuous Drain Current	10	A	
I _{DM}	Pulsed Drain Current (Note 2)	20	A	
E _{AS}	Single Pulsed Avalanche Energy (Note 3)	2	mJ	
dV/dt	Peak Diode Recovery dV/dt (Note 4)	3.8	V/nS	
P _D	Power Dissipation (Note 1)	TO-252	43	W
T _J	Junction Temperature		+150	°C
T _{STG}	Storage Temperature	-55 ~ +150	°C	
R _{θJA}	Thermal Resistance from Junction to Ambient	TO-252	110	°C/W
R _{θJC}	Thermal Resistance from Junction to Case	TO-252 (Note 5)	2.91	°C/W

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature

3. L=0.1mH, I_{AS}=6.3A, V_{DD}=50V, R_G = 25Ω, Starting T_J = 25°C

4. I_{SD} ≤ 10A, di/dt ≤ 200A/μs, V_{DD} ≤ V_{(BR)DSS}, T_J ≤ 25°C

5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.



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■ ELECTRICAL CHARACTERISTICS ($T_A=25^\circ C$, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BVDSS	$V_{GS}=0V, I_D=250\mu A$	100			V
Zero gate voltage drain current	Idss	$V_{DS}=100V, V_{GS}=0V$			1	μA
Gate- Source Leakage Current	Forward	IGSS	$V_{GS}=20V, V_{DS}=0V$		100	nA
	Reverse		$V_{GS}=-20V, V_{DS}=0V$		-100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0		3.0	V
Static Drain-Source On-State Resistance	RDS(ON)	$V_{GS}=4.5V, I_D=5.0A$			110	$m\Omega$
DYNAMIC CHARACTERISTICS						
Input Capacitance	Ciss	$V_{DS}=25V, V_{GS}=0V$ $f= 1.0MHz$		729		pF
Output Capacitance	Coss			48		pF
Reverse Transfer Capacitance	Crss			37		pF
SWITCHING CHARACTERISTICS						
Total Gate Charge (Note 1)	Qg	$V_{DS}=80V, V_{GS}=10V$ $I_D=10A$ (Note 1, 2)		23		nC
Gate-Source Charge	Qgs			4		nC
Gate-Drain Charge	Qgd			6		nC
Turn-On Delay Time (Note 1)	tD(ON)	$V_{DS}=50V, V_{GS}=10V$ $I_D=10A, R_G=6\Omega$ (Note 1, 2)		6		ns
Turn-On Rise Time	tr			15		ns
Turn-Off Delay Time	tD(OFF)			19		ns
Turn-Off Fall Time	tf			18		ns
DRAIN-SOURCE DIODE CHARACTERISTICS						
Maximum Body-Diode Continuous Current	Is				10	A
Maximum Body-Diode Pulsed Current	ISM				20	A
Drain-source diode forward voltage (Note 1)	VSD	$V_{GS} = 0V, I_S = 10A$			1.4	V
Reverse Recovery Time (Note 1)	trr	$I_S=10A, V_{GS}=0V$ $dI/dt=100A/\mu s$		42		ns
Reverse Recovery Charge	Qrr			85		μC

Note:

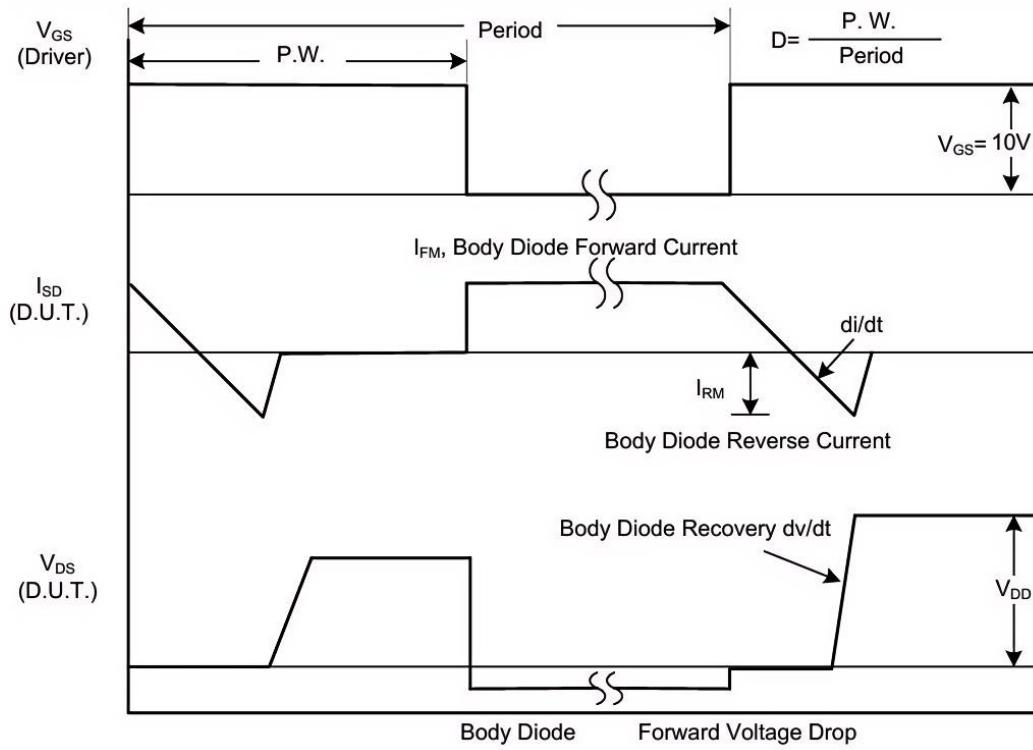
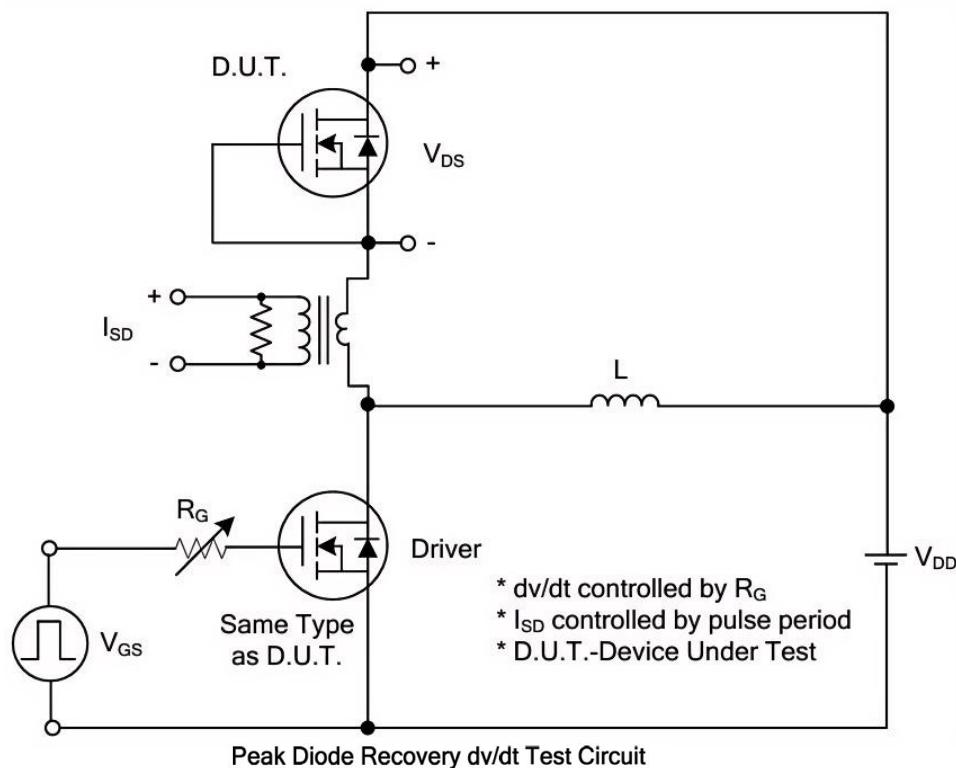
1. Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$.
2. Essentially independent of operating temperature.



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■ TEST CIRCUITS AND WAVEFORMS

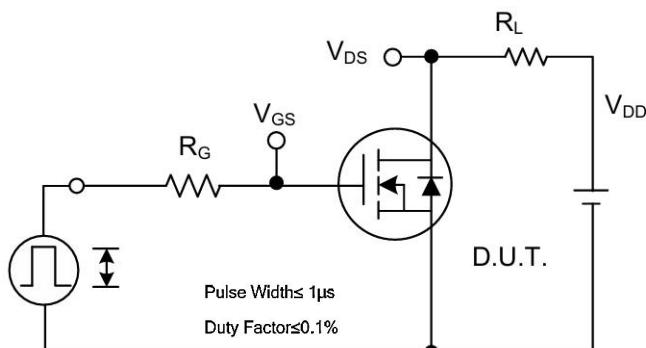




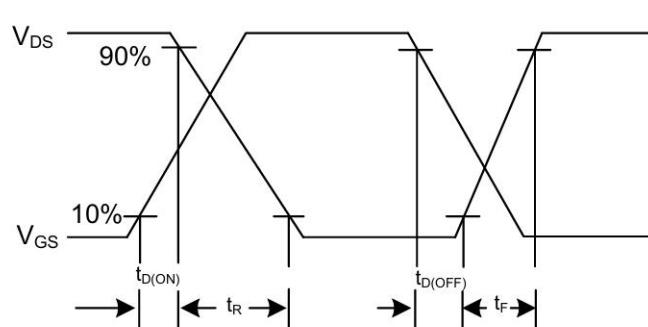
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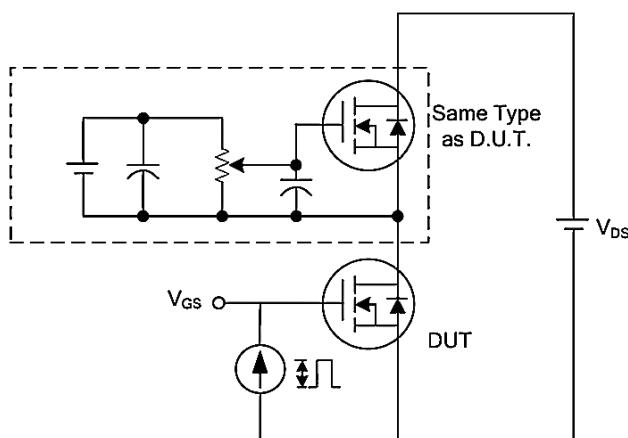
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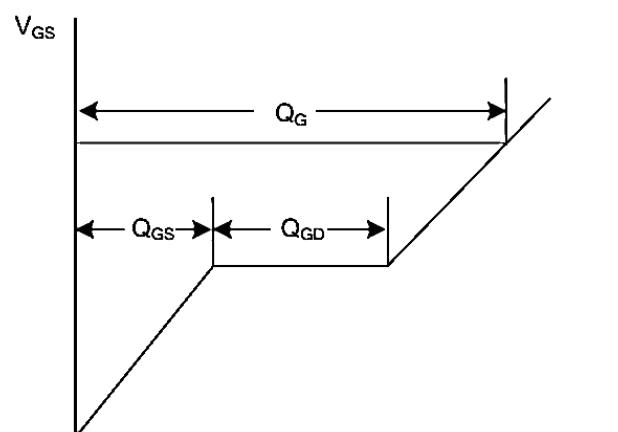
Switching Test Circuit



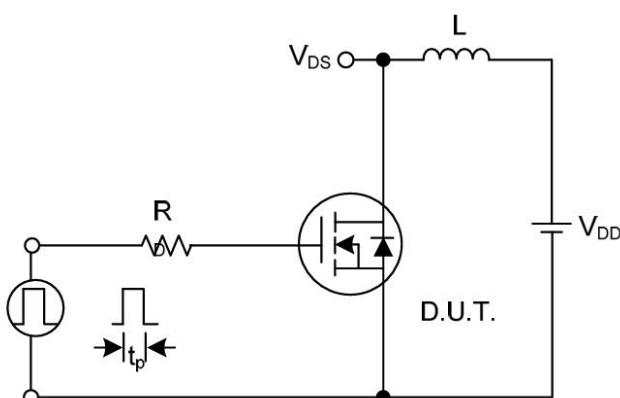
Switching Waveforms



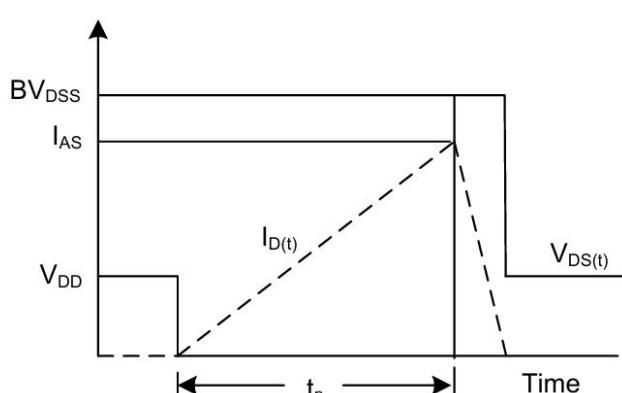
Gate Charge Test Circuit



Charge
Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



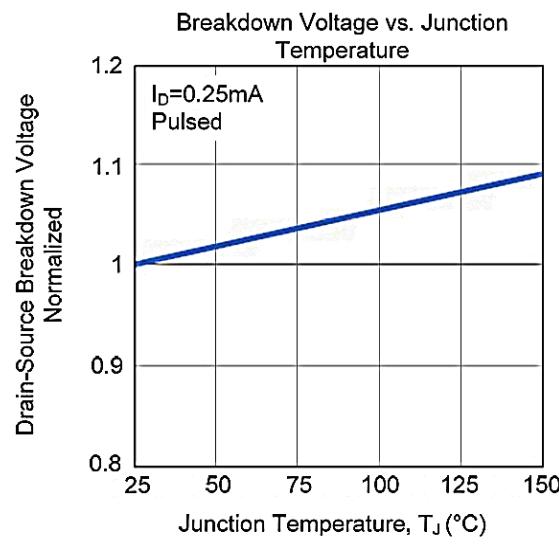
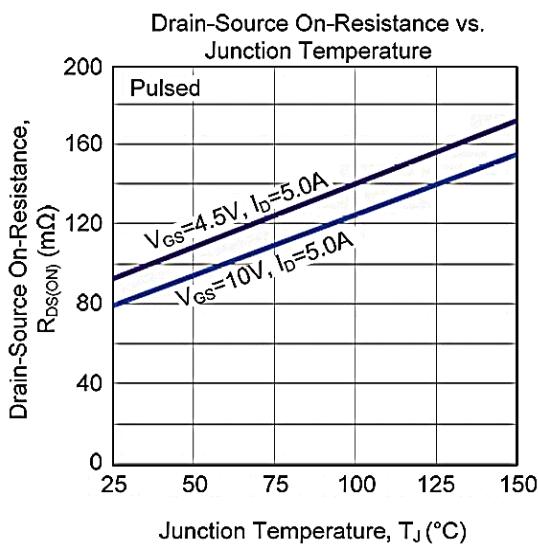
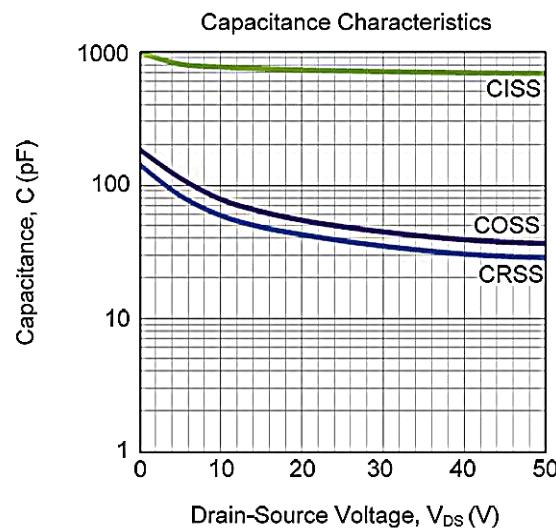
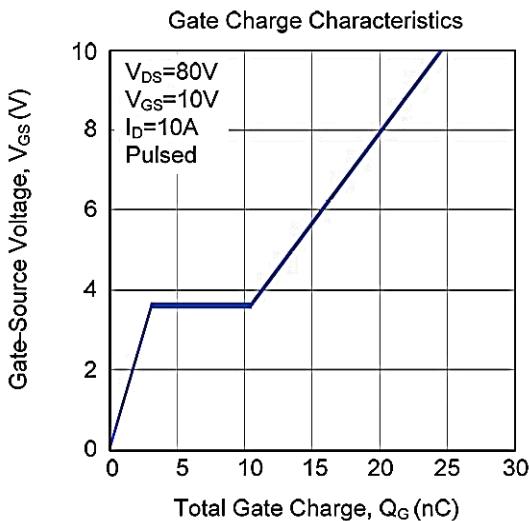
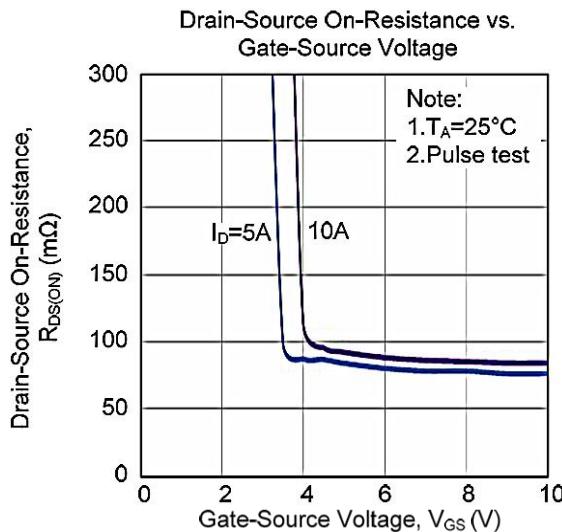
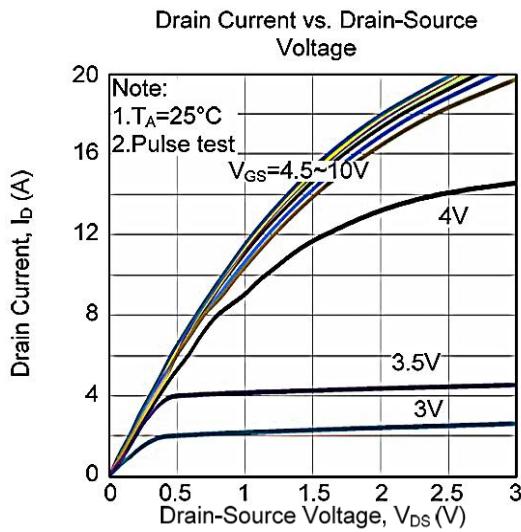
Unclamped Inductive Switching Waveforms



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■ TYPICAL CHARACTERISTICS

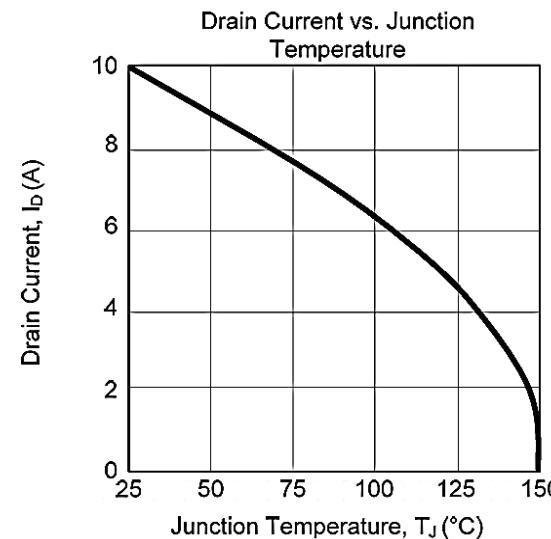
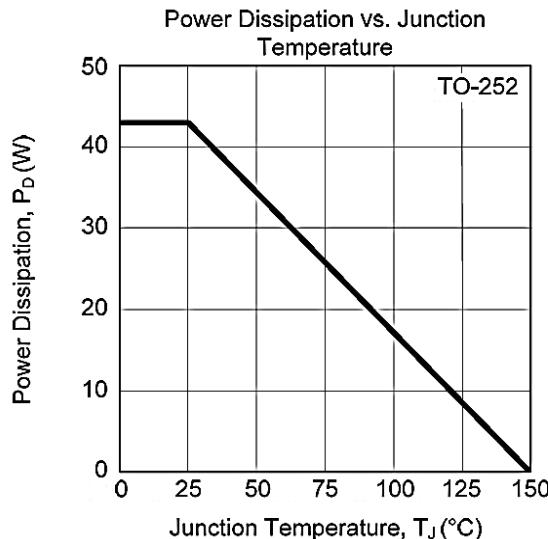
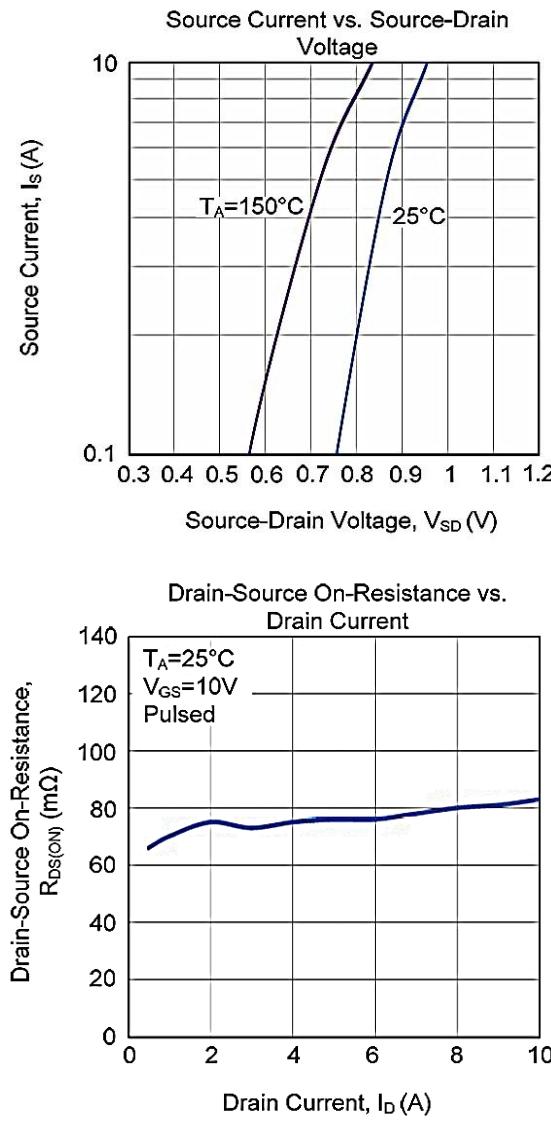
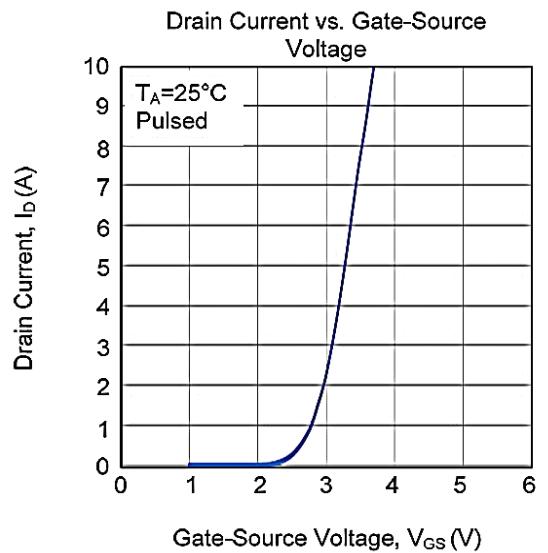
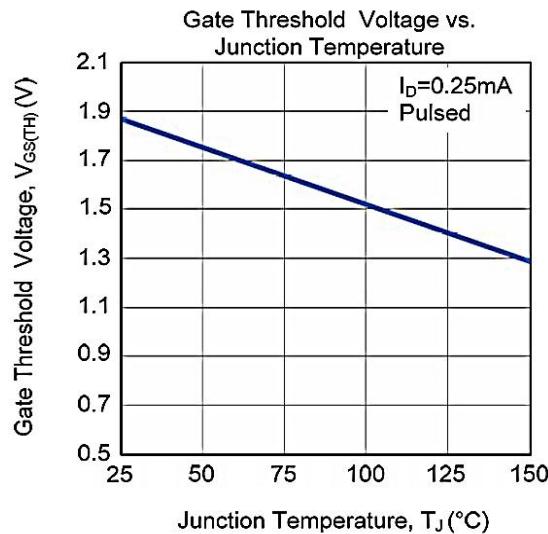




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■ TYPICAL CHARACTERISTICS

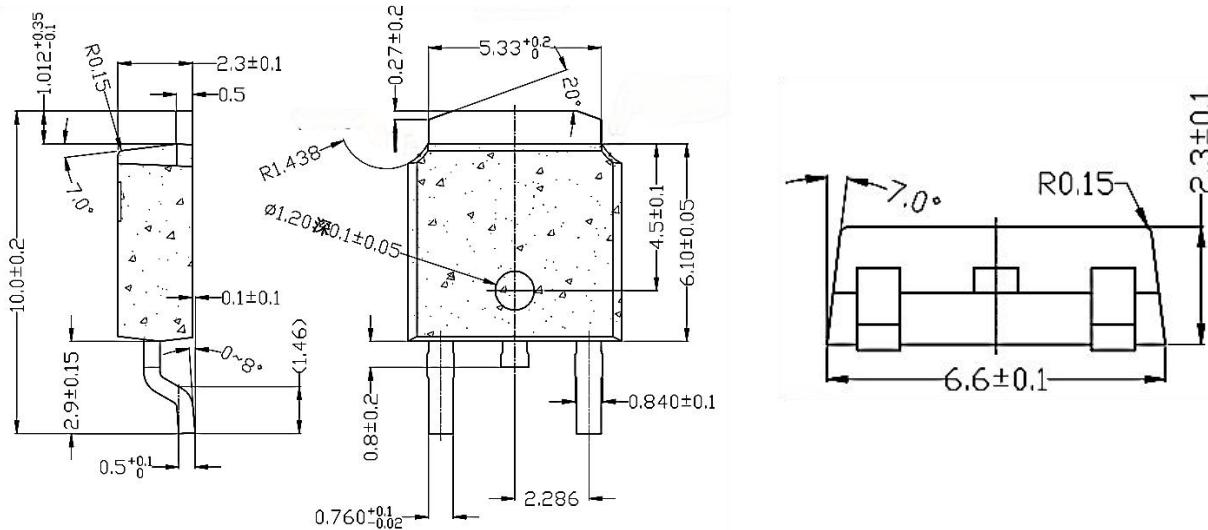




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■ TO - 252 PACKAGE OUTLINE DIMENSIONS



■ TO - 252 PACKING INFORMATION



Package version	Reel dimensions $\Phi \times H$ (mm)	Per Reel (pcs)	Reels per box	Inner box dimensions L×W×H (mm)	Outer box (pcs)	Outer box dimensions L×W×H (mm)
TO-252	$\Phi 330 \times 20$	2500	2	360×340×50	25000	375×375×280